

| L Number | Hits | Search Text | DB | Time stamp |
|----------|------|--|---|------------------|
| 2 | 1350 | (257/777).CCLS. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/10/27 16:54 |
| 3 | 2613 | 257/777 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/10/27 16:55 |
| 4 | 4196 | 257/778 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/10/27 17:12 |
| 5 | 1743 | 257/779 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/10/27 17:30 |
| 6 | 2057 | 257/780 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/10/27 17:45 |
| 7 | 1063 | 257/781 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/10/27 18:03 |
| 8 | 4196 | 257/778 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/10/27 18:01 |
| 9 | 3831 | 257/723 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/10/27 18:12 |
| 10 | 1 | | USPAT | 2004/10/27 18:06 |
| 11 | 1 | | USPAT | 2004/10/27 18:07 |
| 12 | 1 | | USPAT | 2004/10/27 18:07 |
| 13 | 2661 | 257/724 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/10/27 18:30 |
| 14 | 1209 | 257/685 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/10/27 18:47 |
| 15 | 2825 | 257/686 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/10/27 19:06 |
| 16 | 2768 | 257/690 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/10/27 19:23 |
| 17 | 3612 | (semiconductor or die or chip or Ic) with wir\$3 and solder near (ball or bump) and (encapsulat\$3 or mold\$3) | USPAT | 2004/10/27 19:08 |
| 18 | 487 | ((semiconductor or die or chip or Ic) with wir\$3 and solder near (ball or bump) and (encapsulat\$3 or mold\$3)) and (ball or bump) with (big or large) | USPAT | 2004/10/27 19:09 |

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|----|------|-----------|---|------------------|
| 19 | 2749 | 257/700 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/10/27 20:00 |
| 20 | 2211 | 438/108 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/10/27 20:25 |
| 21 | 37 | "5844315" | USPAT | 2004/10/27 20:12 |
| 22 | 1 | | USPAT | 2004/10/27 20:09 |
| 23 | 1 | | USPAT | 2004/10/27 20:09 |
| 24 | 1 | | USPAT | 2004/10/27 20:09 |
| 25 | 1 | | USPAT | 2004/10/27 20:09 |
| 26 | 1 | | USPAT | 2004/10/27 20:09 |
| 27 | 1 | | USPAT | 2004/10/27 20:09 |
| 28 | 1 | | USPAT | 2004/10/27 20:09 |
| 29 | 1 | | USPAT | 2004/10/27 20:10 |
| 30 | 1 | | USPAT | 2004/10/27 20:11 |
| 31 | 1 | | USPAT | 2004/10/27 20:11 |
| 32 | 35 | "5608265" | USPAT | 2004/10/27 20:12 |
| 33 | 1045 | 438/109 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/10/27 20:42 |
| 34 | 3850 | 361/760 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/10/27 20:44 |